



Material Content Data Sheet



Sales Product Name				IPZ40N04S5L-2R8		Issued		20. July 2018	
MA#				MA001338262					
Package				PG-TSDSON-8-33		Weight*		36.49 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.549	1.50	1.50	15038	15038	
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		85		
	non noble metal	zinc	7440-66-6	0.012	0.03		341		
	non noble metal	iron	7439-89-6	0.249	0.68		6818		
wire	non noble metal	copper	7440-50-8	10.102	27.68	28.40	276835	284079	
	noble metal	gold	7440-57-5	0.029	0.08	0.08	804	804	
	encapsulation	organic material	carbon black	1333-86-4	0.036	0.10		993	
encapsulation	plastics	epoxy resin	-	1.867	5.12		51153		
	inorganic material	silicondioxide	60676-86-0	16.220	44.46	49.68	444486	496632	
leadfinish	non noble metal	tin	7440-31-5	0.400	1.10	1.10	10969	10969	
plating	noble metal	silver	7440-22-4	0.086	0.23	0.23	2347	2347	
solder	noble metal	silver	7440-22-4	0.020	0.05		547		
	non noble metal	tin	7440-31-5	0.016	0.04		438		
	non noble metal	lead	7439-92-1	0.763	2.09	2.18	20906	21891	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		16		
	non noble metal	zinc	7440-66-6	0.002	0.01		64		
	non noble metal	iron	7439-89-6	0.047	0.13		1287		
	non noble metal	copper	7440-50-8	1.908	5.23	5.37	52276	53643	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		34		
	non noble metal	zinc	7440-66-6	0.005	0.01		138		
	non noble metal	iron	7439-89-6	0.100	0.28		2750		
	non noble metal	copper	7440-50-8	4.075	11.17	11.46	111675	114597	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com